

Listing of Claims:

1. (currently amended) A power semiconductor module for mounting on a flat body, comprising a plurality of partial modules, each of said partial modules having:

a base plate;

a framelike housing;

terminal elements for load terminals and auxiliary terminals;

at least one electrically insulated substrate disposed inside said housing on said base plate, said substrate having an insulation body with a plurality of metal connection tracks located therein and insulated from one another, and power semiconductor components, located on said connection tracks and electrically connected thereto;

at least two open-slotlike recesses on a side thereof, and positioned so that, when said partial modules are assembled into a power semiconductor module, said recesses in sides of adjacent partial modules face one another to form closed slots;
and

~~means~~ a cap for connecting adjacent partial modules to one another;

said cap having round slotlike recesses for receiving screws, which, in the abutting region of said partial modules, are aligned with said recesses that form said slots therein.

2. (canceled)

~~2~~ ~~3.~~ (currently amended) The power semiconductor module of claim ~~2~~ 1,
wherein

said cap is connected to said partial modules by means of snap-detent connections, said housing has detent lugs, and said cap has abutments formed to cooperate with said detent lugs.

4. - 5. (canceled)

~~3~~ ~~6.~~ (original) The power semiconductor module of claim 1, wherein
each of said partial modules has, on a first side adjacent to another partial module, at least one detent lug, and on a second, opposite, side thereof has at least one abutment adapted to cooperate with a detent lug in an adjacent partial module

~~4~~ ~~7.~~ (original) The power semiconductor module of claim 1, wherein
said means for connecting comprises fixing connections.

~~5~~ ~~8.~~ (original) The power semiconductor module of claim ~~7~~ 4, wherein
said fixing connections include a snap-detent connection for connection of
a first partial module to an adjacent partial module.

~~6~~ ~~9.~~ (original) The power semiconductor module of claim ~~8~~ 5, wherein
each of said partial modules has at least two open-slotlike recesses on a side thereof, and positioned so that, when said partial modules are assembled into a

power semiconductor module, said recesses in said sides of adjoining partial modules face one another to form closed slots.

~~7~~ 10. (original) The power semiconductor module of claim ~~7~~⁴, wherein said fixing connections include a rail that covers all said recesses and said slots formed thereby in adjacent partial modules.